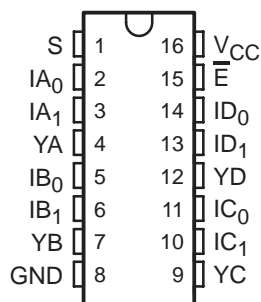


TS3L100 QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

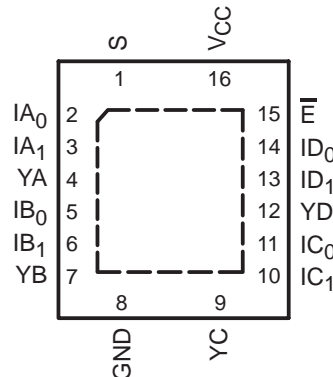
SCDS161A – MAY 2004 – REVISED OCTOBER 2004

- Wide Bandwidth (BW = 350 MHz Min)
- Low Differential Crosstalk ($X_{TALK} = -68$ dB Typ)
- Low Power Consumption ($I_{CC} = 10$ μ A Max)
- Bidirectional Data Flow, With Near-Zero Propagation Delay
- Low ON-State Resistance ($r_{ON} = 5$ Ω Typ)
- Rail-to-Rail Switching on Data I/O Ports (0 to V_{CC})
- V_{CC} Operating Range From 3 V to 3.6 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Data and Control Inputs Have Undershoot Clamp Diodes
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- Suitable for Both 10 Base-T/100 Base-T Signaling

D, DBQ, DGV, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



description/ordering information

The TI TS3L100 LAN switch is a 4-bit 1-of-2 multiplexer/demultiplexer with a single switch-enable (\bar{E}) input. When \bar{E} is low, the switch is enabled and the I port is connected to the Y port. When \bar{E} is high, the switch is disabled and the high-impedance state exists between the I and Y ports. The select (S) input controls the data path of the multiplexer/demultiplexer.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	QFN – RGY	Tape and reel	TS3L100RGYR	TK100
		Tube	TS3L100D	TS3L100
	SOIC – D	Tape and reel	TS3L100DR	
		SSOP (QSOP) – DBQ	Tape and reel	TS3L100DBQR
	TSSOP – PW	Tube	TS3L100PW	TK100
		Tape and reel	TS3L100PWR	
TVSOP – DGV	Tape and reel	TS3L100DGV	TK100	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated

TS3L100

QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

description/ordering information (continued)

This device can be used to replace mechanical relays in LAN applications. This device has low r_{on} , wide bandwidth, and low differential crosstalk, making it suitable for 10 Base-T, 100 Base-T, and various other LAN applications.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, \bar{E} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

INPUTS		INPUT/OUTPUT YX	FUNCTION
\bar{E}	S		
L	L	IX_0	$YX = IX_0$
L	H	IX_1	$YX = IX_1$
H	X	Z	Disconnect

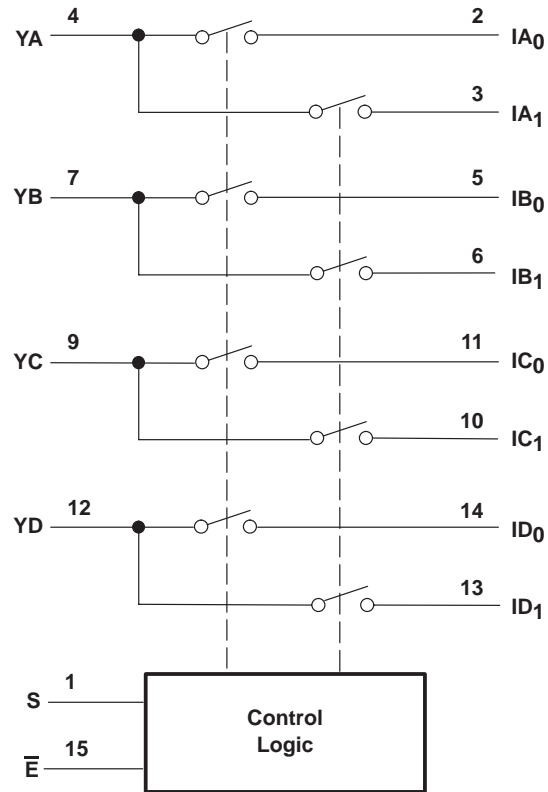
PIN DESCRIPTIONS

PIN NAME	DESCRIPTION
IAn–IDn	Data I/Os
S	Select input
\bar{E}	Enable input
YA–YD	Data I/Os

TS3L100
QUAD SPDT WIDE-BANDWIDTH LAN SWITCH
WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

logic diagram (positive logic)



TS3L100

QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Control input voltage range, V_{IN} (see Notes 1 and 2)	–0.5 V to 4.6 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1, 2, and 3)	–0.5 V to 4.6 V
Control input clamp current, I_{IK} ($V_{IN} < 0$)	–50 mA
I/O port clamp current, $I_{I/OK}$ ($V_{I/O} < 0$)	–50 mA
ON-state switch current, $I_{I/O}$ (see Note 4)	±128 mA
Continuous current through V_{CC} or GND terminals	±100 mA
Package thermal impedance, θ_{JA} (see Note 5):	
D package	73°C/W
DB package	82°C/W
DBQ package	90°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltages are with respect to ground, unless otherwise specified.
 2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 3. V_I and V_O are used to denote specific conditions for $V_{I/O}$.
 4. I_I and I_O are used to denote specific conditions for $I_{I/O}$.
 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 6)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	3	3.6	V
V_{IH}	High-level control input voltage (\bar{E} , S)	2	V_{CC}	V
V_{IL}	Low-level control input voltage (\bar{E} , S)	0	0.8	V
T_A	Operating free-air temperature	0	70	°C

NOTE 6: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



TS3L100

QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

**electrical characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}	\bar{E} , S	V _{CC} = 3 V,	I _{IN} = -18 mA			-1.8	V
V _{hys}	\bar{E} , S				150		mV
I _{IH}	\bar{E} , S	V _{CC} = 3.6 V,	V _{IN} = V _{CC}			±1	μA
I _{IL}	\bar{E} , S	V _{CC} = 3.6 V,	V _{IN} = GND			±1	μA
I _{OZ} ‡		V _{CC} = 3.6 V,	V _O = 0 to 3.6 V, V _I = 0, Switch OFF			±1	μA
I _{OS} §		V _{CC} = 3.6 V,	V _O = 0 to 0.5 V _{CC} , V _I = 0, Switch ON	50			mA
I _{off}		V _{CC} = 0,	V _O = 0 to 3.6 V, V _I = 0			15	μA
I _{CC}		V _{CC} = 3.6 V,	I _{I/O} = 0, Switch ON or OFF		0.1	10	μA
ΔI _{CC}	\bar{E} , S	V _{CC} = 3.6 V,	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND			750	μA
I _{CCD}		V _{CC} = 3.6 V,	I and Y ports open, V _{IN} input switching 50% duty cycle			0.45	mA/ MHz
C _{IN}	\bar{E} , S	f = 1 MHz			3		pF
C _{OFF}	I port	V _I = 0,	f = 1 MHz, Outputs open, Switch OFF		5		pF
	Y port				10		
C _{ON}		V _I = 0,	f = 1 MHz, Outputs open, Switch ON		17		pF
r _{on}		V _{CC} = 3 V	V _I = 0 V,	I _O = 48 mA	5	7	Ω
			V _I = 2 V,	I _O = 15 mA	10	15	
Δr _{on}		V _I = 3 V,	Switch ON, I _O = 15 mA		1		Ω

V_I, V_O, I_I, and I_O refer to I/O pins. V_{IN} refers to the control inputs.

† All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

§ The I_{OS} test is applicable to only one ON channel at a time. The duration of this test is less than one second.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V, R_L = 100 Ω, C_L = 35 pF (unless otherwise noted) (see Figure 4)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t _{ON}	S	Y	1	7.5	ns
t _{OFF}	S	Y	1	3.5	ns

† All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.

**dynamic characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted)**

PARAMETER	TEST CONDITIONS			TYP†	UNIT
X _{TALK} (Diff)	R _L = 100 Ω,	f = 10 MHz, see Figure 8,	t _r = t _f = 2 ns	-55	dB
X _{TALK}	R _L = 100 Ω,	f = 30 MHz, see Figure 6		-68	dB
O _{IRR}	R _L = 100 Ω,	f = 30 MHz, see Figure 7		-42	dB
BW	R _L = 100 Ω, see Figure 5			350	MHz

† All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.



TS3L100 QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

OPERATING CHARACTERISTICS

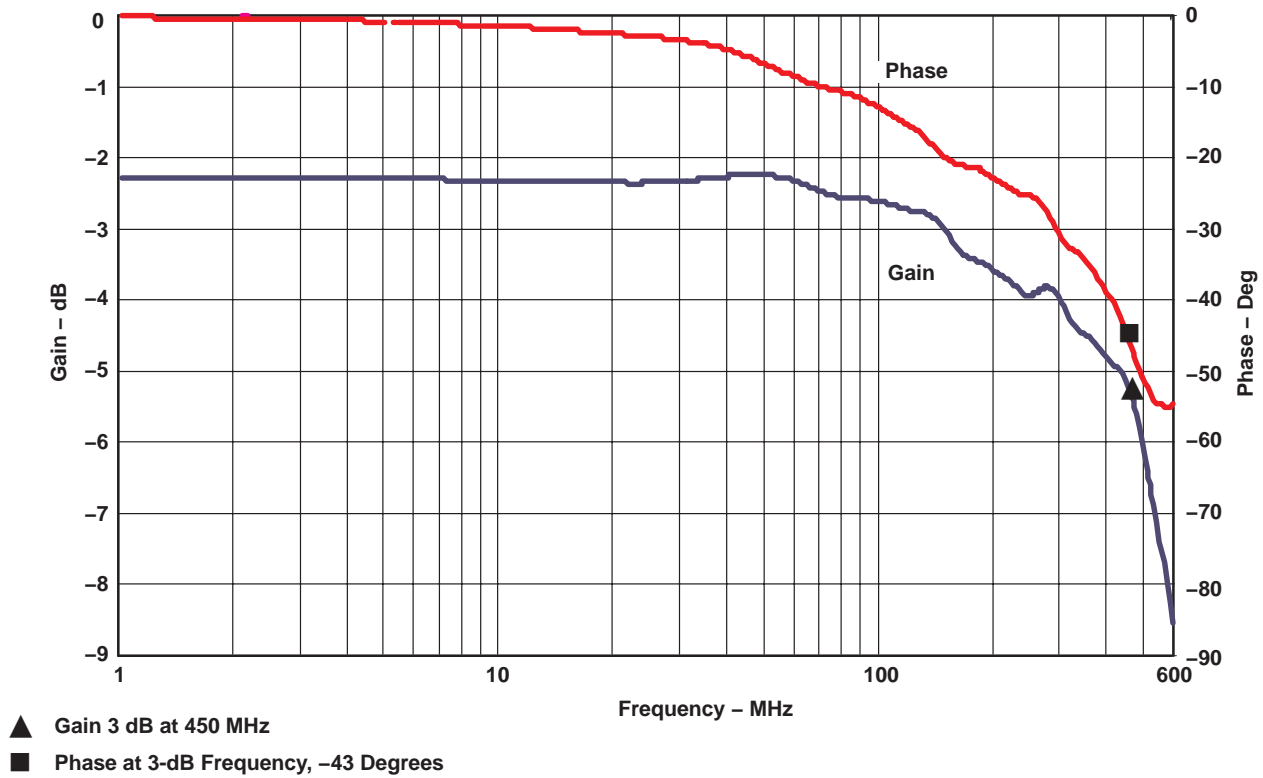
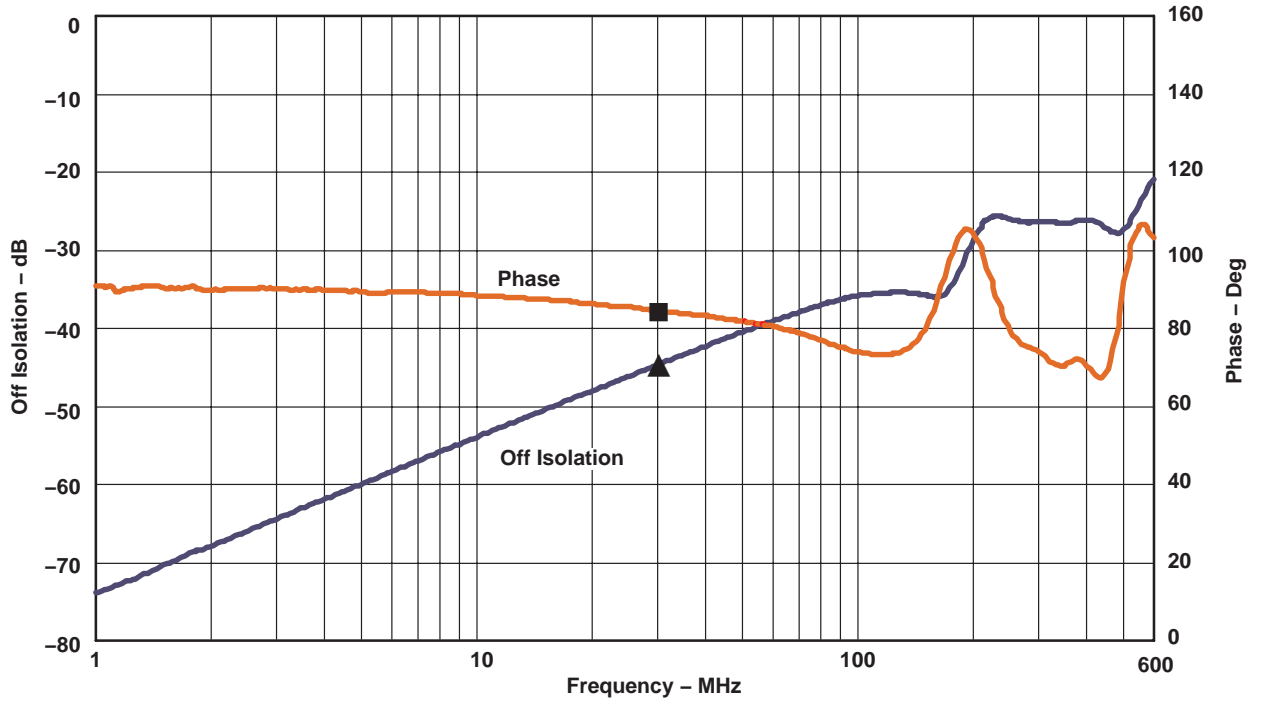


Figure 1. Gain/Phase vs Frequency

OPERATING CHARACTERISTICS



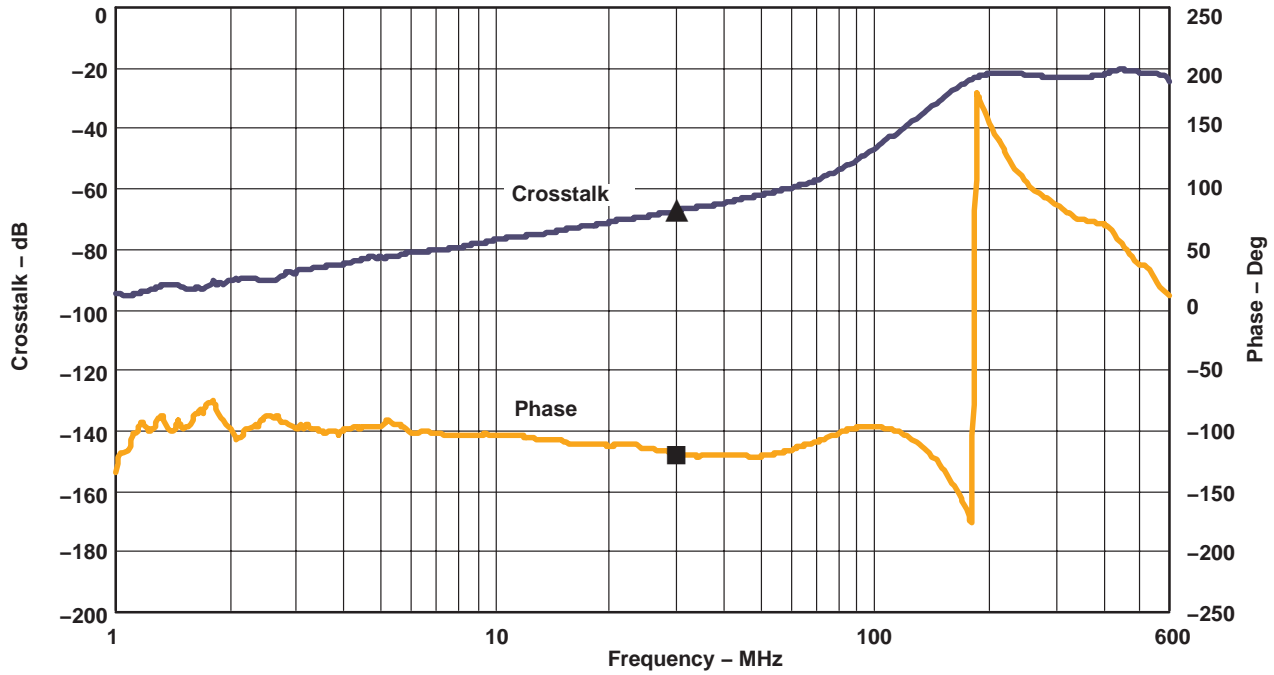
- ▲ Off Isolation at 30 MHz, -44.6 dB
- Phase at 30 MHz, 84.41 Degrees

Figure 2. Off Isolation vs Frequency

TS3L100 QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

OPERATING CHARACTERISTICS



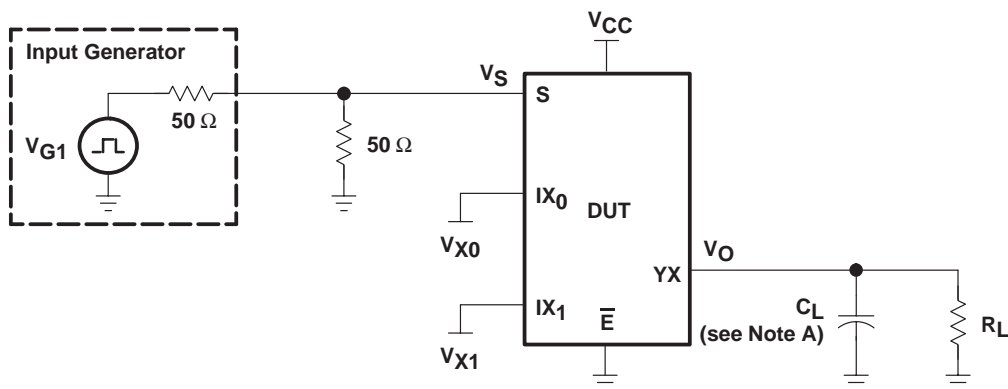
- ▲ Crosstalk at 30 MHz, -67.3 dB
- Phase at 30 MHz, -118.4 Degrees

Figure 3. Crosstalk vs Frequency

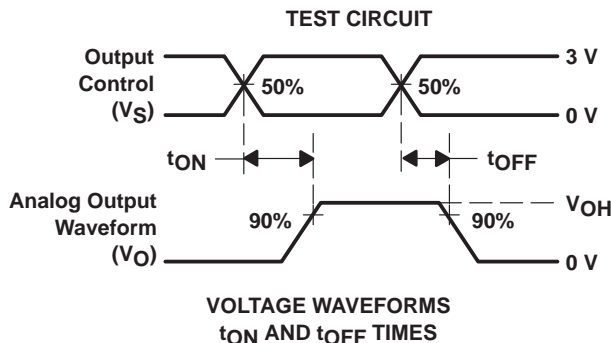
TS3L100 QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

PARAMETER MEASUREMENT INFORMATION



TEST	VCC	RL	CL	VX0	VX1
tON	3.3 V ± 0.3 V	100 Ω	35 pF	GND	3 V
	3.3 V ± 0.3 V	100 Ω	35 pF	3 V	GND
tOFF	3.3 V ± 0.3 V	100 Ω	35 pF	GND	3 V
	3.3 V ± 0.3 V	100 Ω	35 pF	3 V	GND



- NOTES: A. C_L includes probe and jig capacitance.
 B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 C. The outputs are measured one at a time, with one transition per measurement.

Figure 4. Test Circuit and Voltage Waveforms

TS3L100 QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

PARAMETER MEASUREMENT INFORMATION

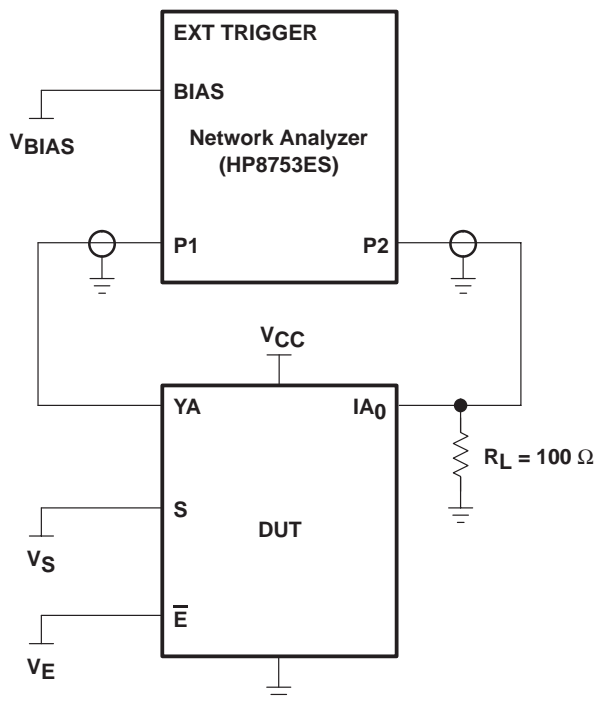


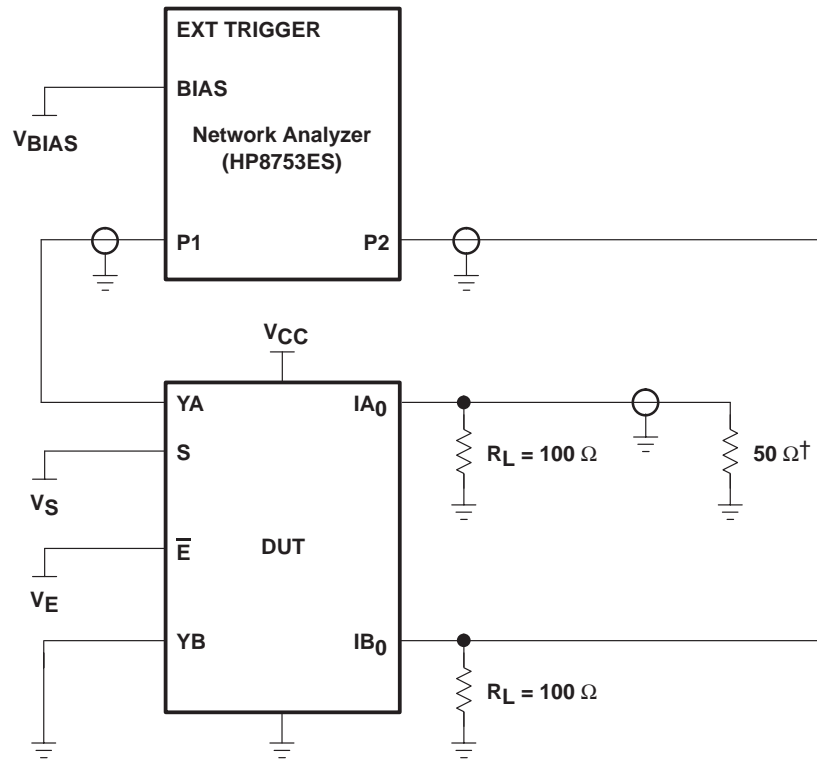
Figure 5. Test Circuit for Frequency Response (BW)

Frequency response is measured at the output of the ON channel. For example, when $V_S = 0$, $V_E = 0$, and YA is the input, the output is measured at IA₀. All unused analog I/O ports are left open.

HP8753ES setup

Average = 4
RBW = 3 kHz
 $V_{BIAS} = 0.35$ V
ST = 2 s
P1 = 0 dBm

PARAMETER MEASUREMENT INFORMATION



† A 50-Ω termination resistor is needed for the network analyzer.

Figure 6. Test Circuit for Crosstalk (X_{TALK})

Crosstalk is measured at the output of the nonadjacent ON channel. For example, when $V_S = 0$, $V_E = 0$, and YA is the input, the output is measured at IB_0 . All unused analog input (Y) ports are connected to GND and output (I) ports are connected to GND through 50-Ω pulldown resistors.

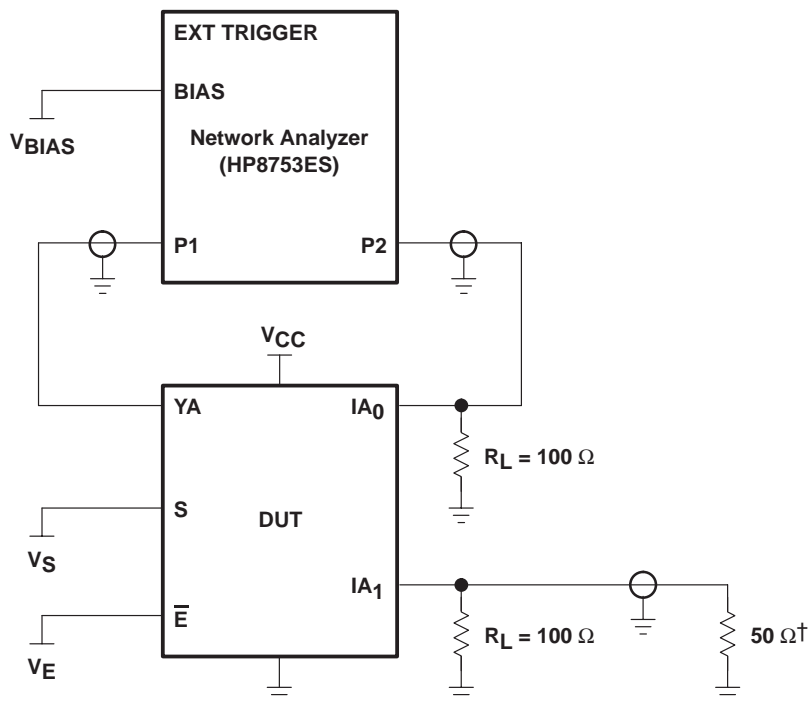
HP8753ES setup

- Average = 4
- RBW = 3 kHz
- $V_{BIAS} = 0.35\text{ V}$
- ST = 2 s
- P1 = 0 dBm

TS3L100 QUAD SPDT WIDE-BANDWIDTH LAN SWITCH WITH LOW ON-STATE RESISTANCE

SCDS161A – MAY 2004 – REVISED OCTOBER 2004

PARAMETER MEASUREMENT INFORMATION



† A 50-Ω termination resistor is needed for the network analyzer.

Figure 7. Test Circuit for Off Isolation (O_{IRR})

OFF isolation is measured at the output of the OFF channel. For example, when $V_S = V_{CC}$, $V_E = 0$, and YA is the input, the output is measured at IA₀. All unused analog input (Y) ports are left open and output (I) ports are connected to GND through 50-Ω pulldown resistors.

HP8753ES setup

Average = 4
 RBW = 3 kHz
 $V_{BIAS} = 0.35$ V
 ST = 2 s
 P1 = 0 dBm

PARAMETER MEASUREMENT INFORMATION

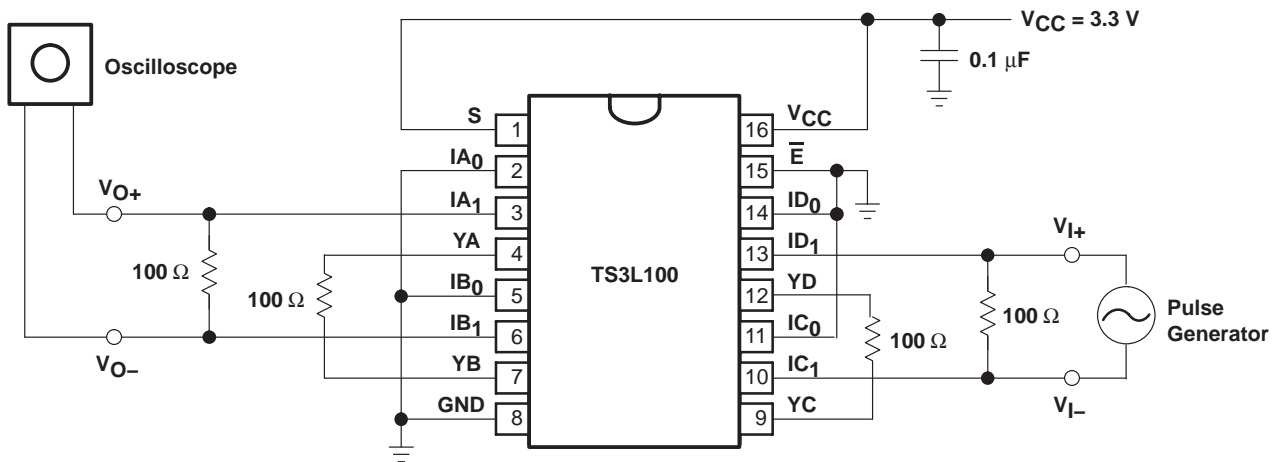


Figure 8. Differential Crosstalk Measurement

Differential crosstalk is a measure of coupling noise between a transmit and receive pair in the LAN application. Differential crosstalk depends on the edge rate, frequency, and load. This is calculated from the equation, $X_{TALK}(Diff) \text{ db} = 20 \log V_O(Diff)/V_I(Diff)$, where $V_O(Diff)$ is the differential output voltage and $V_I(Diff)$ is the differential input voltage.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TS3L100DBQR	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	TK100
TS3L100DBQR.B	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	TK100
TS3L100DGVR	Active	Production	TVSOP (DGV) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TK100
TS3L100DGVR.B	Active	Production	TVSOP (DGV) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TK100
TS3L100DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TS3L100
TS3L100DR.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TS3L100
TS3L100PW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TK100
TS3L100PW.B	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TK100
TS3L100PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TK100
TS3L100PWR.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TK100
TS3L100RGYR	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	TK100
TS3L100RGYR.B	Active	Production	VQFN (RGY) 16	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	TK100

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS3L100DBQR	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
TS3L100DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
TS3L100DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TS3L100PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TS3L100RGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS3L100DBQR	SSOP	DBQ	16	2500	353.0	353.0	32.0
TS3L100DGVR	TVSOP	DGV	16	2000	353.0	353.0	32.0
TS3L100DR	SOIC	D	16	2500	340.5	336.1	32.0
TS3L100PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
TS3L100RGYR	VQFN	RGY	16	3000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TS3L100PW	PW	TSSOP	16	90	530	10.2	3600	3.5
TS3L100PW.B	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

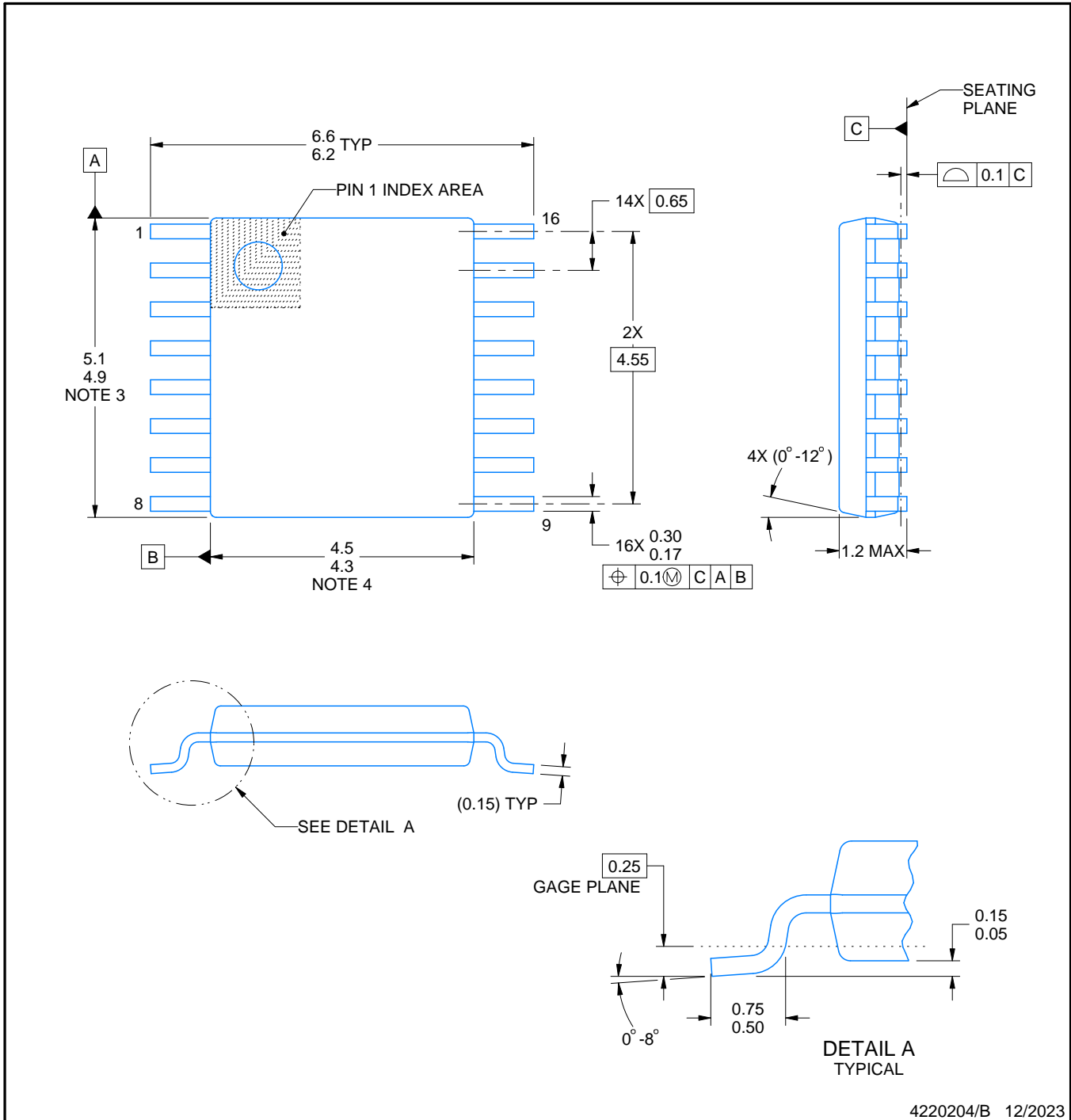
DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194



4220204/B 12/2023

NOTES:

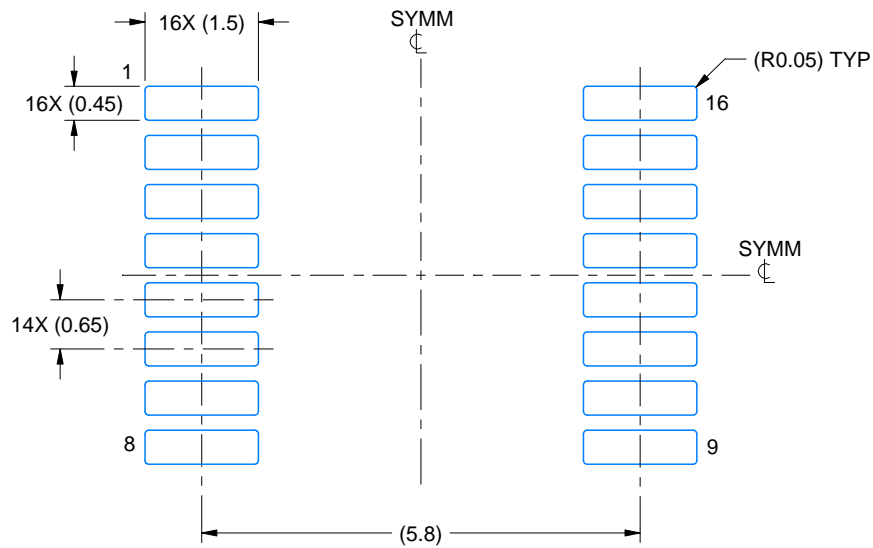
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

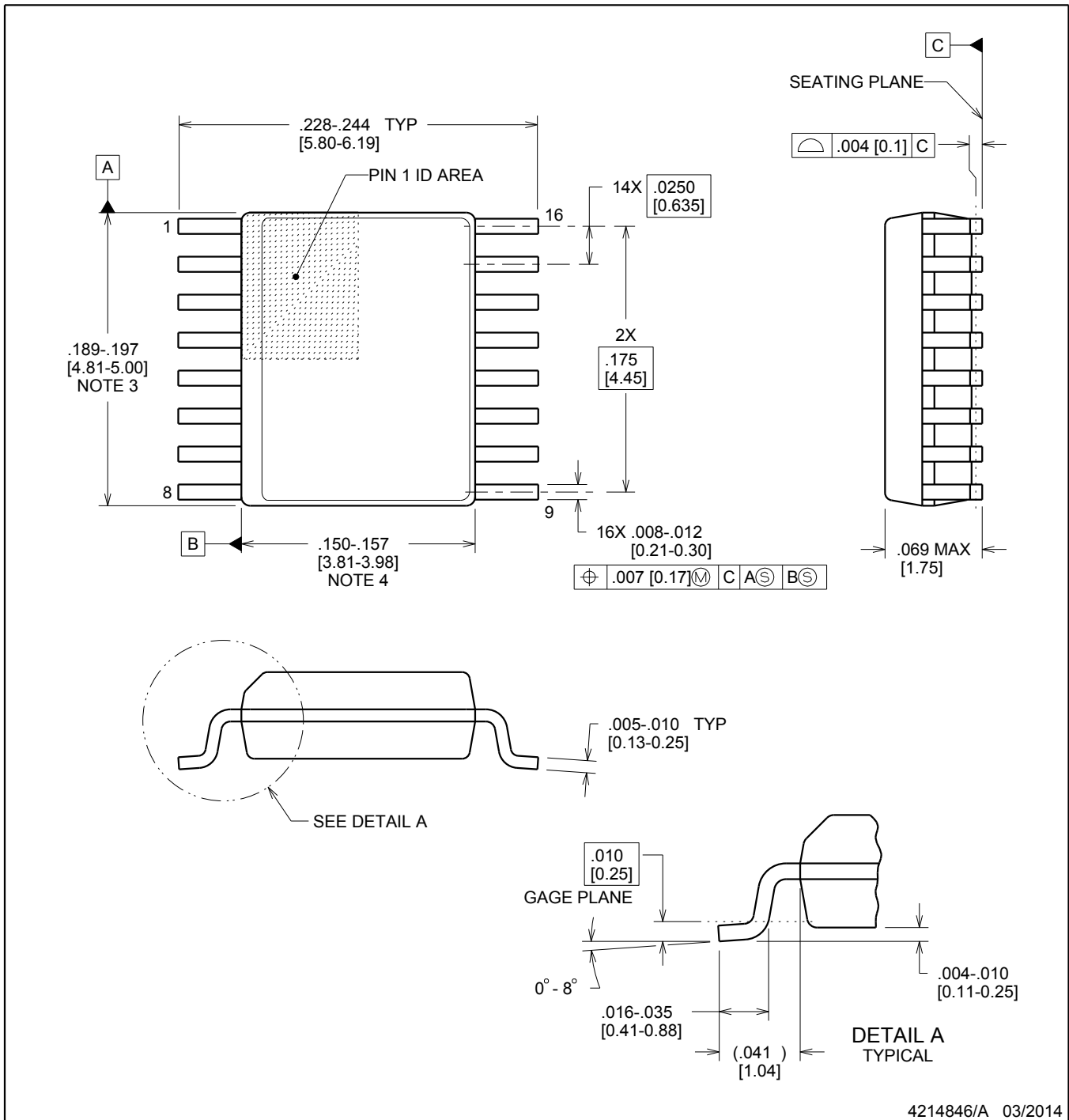


DBQ0016A

PACKAGE OUTLINE

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



NOTES:

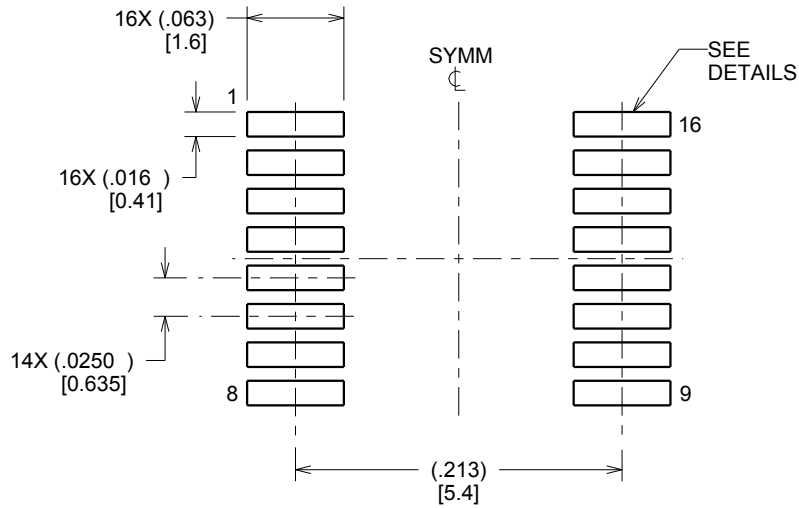
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MO-137, variation AB.

EXAMPLE BOARD LAYOUT

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4214846/A 03/2014

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBQ0016A

SSOP - 1.75 mm max height

SHRINK SMALL-OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.127 MM] THICK STENCIL
SCALE:8X

4214846/A 03/2014

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - G. Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-3/P 03/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025